

Sub-5 nm Patterning and Applications by Nanoimprint Lithography and Helium Ion Beam Lithography

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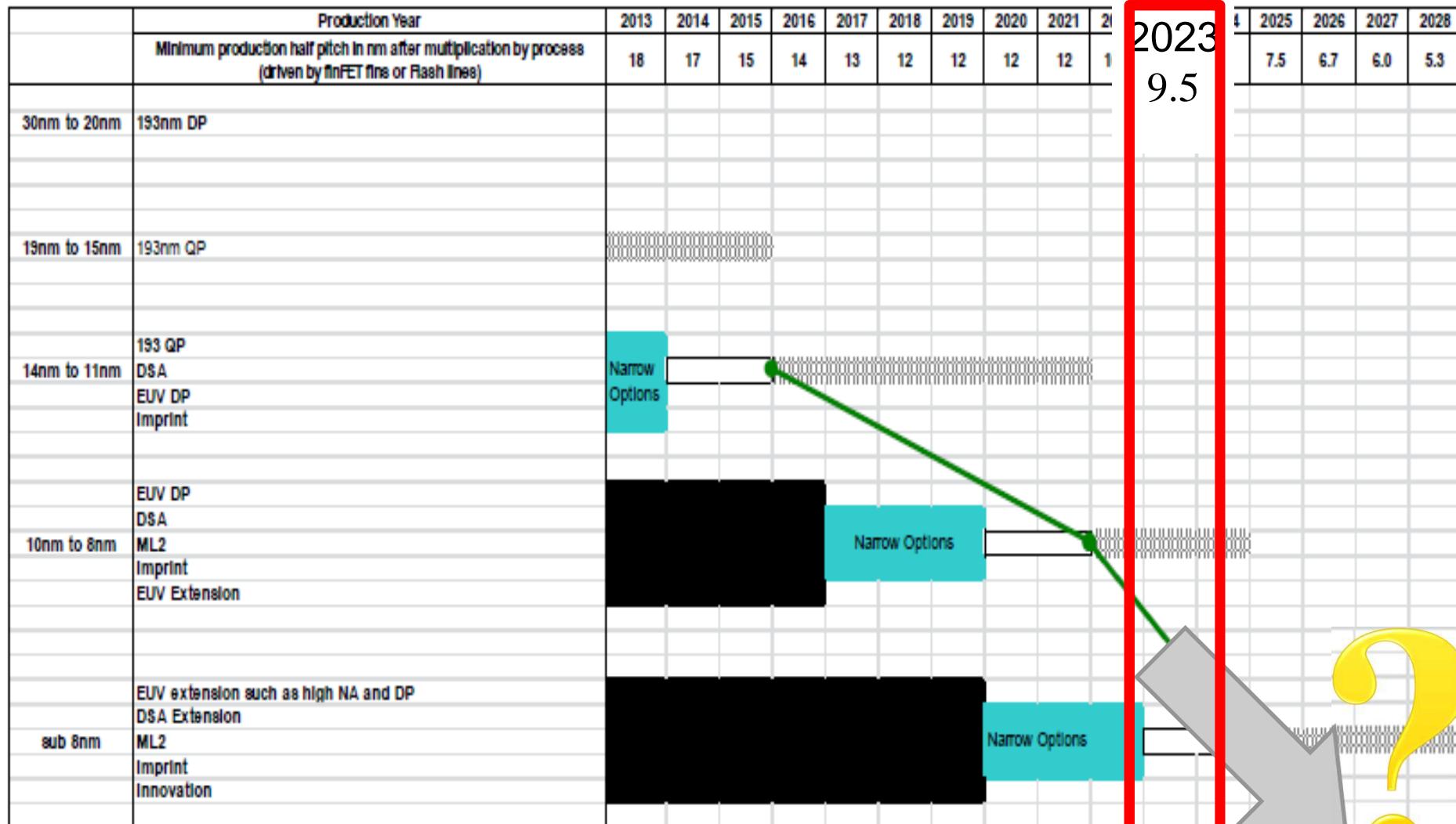
²Department of Mechanical Engineering, University Of Hong Kong

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- Motivation
- Sub-5 nm lithography
 - Helium ion beam lithography
 - Nanoimprint lithography
- 5 nm graphene nanoribbons
 - Line-edge benchmarking using Raman spectroscopy
 - GNR FET and sensor
- Summary

Single-digit Nanometer Era

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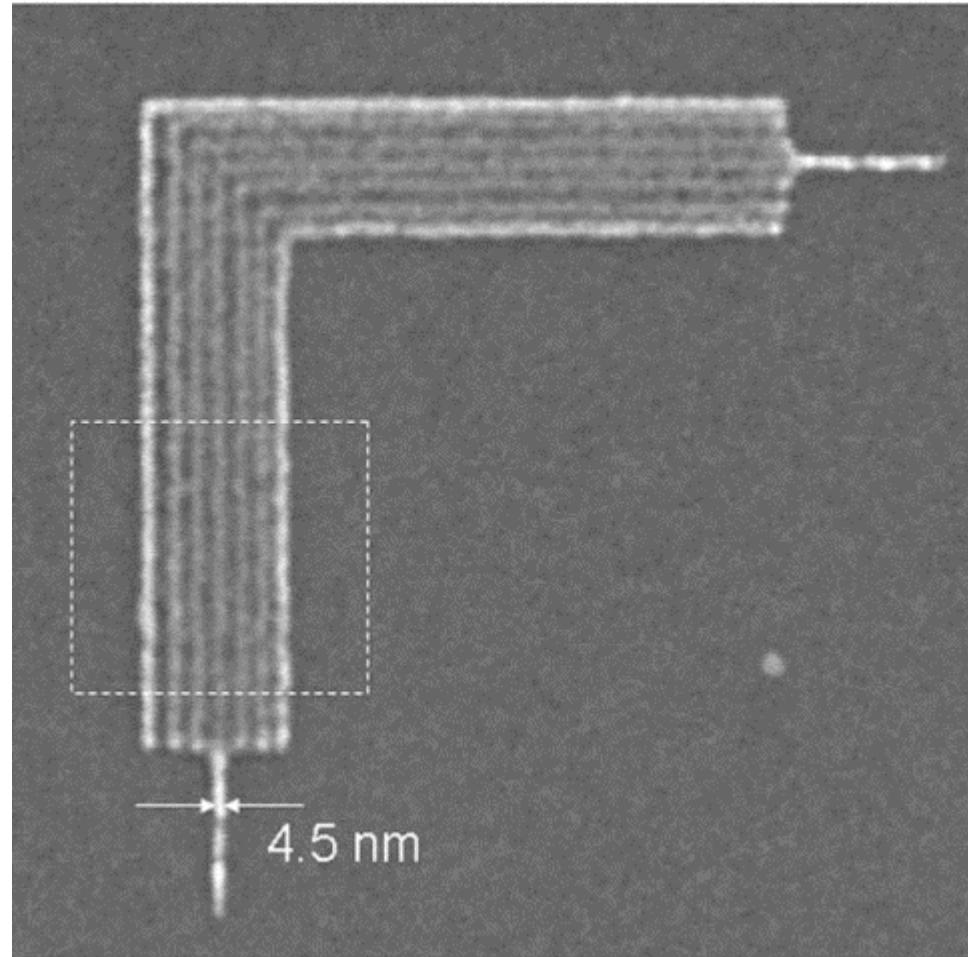


*Lithography for flash, ITRS roadmap 2013 update

How to Achieve Better Resolution than Electron Beam Lithography?

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Smallest half-pitch patterned by EBL in HSQ: 4.5 nm



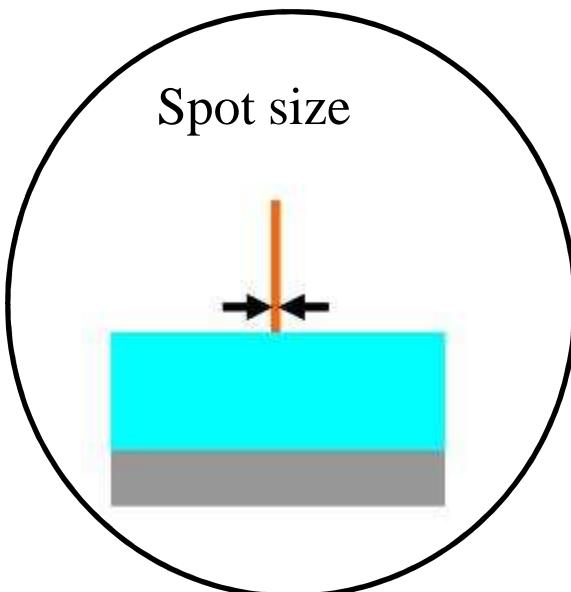
Yang et al, J. Vac. Sci. Techno. 2009

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The Limiting Factor of EBL

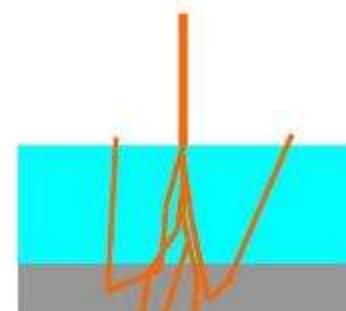
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Resolution limiting factors of electron beam (with a perfect resist):

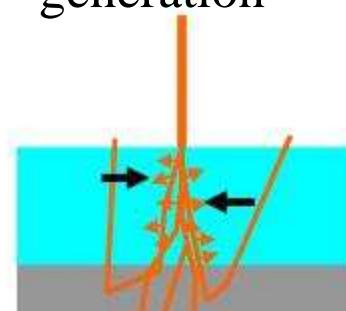


~ 4 nm

Beam scattering
(forward and backward)



Second electron
generation



Proximity effect 10 nm ~ microns

Overall beam spot diameter

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$$d = \sqrt{d_g^2 + d_s^2 + d_c^2 + d_d^2} \quad (\text{assume no astigmatism})$$

$$d_g = \frac{d_v}{M}$$

d_v: virtual source diameter
M: demagnification

$$d_s = \frac{1}{2} C_s \alpha^3$$

Spherical aberration

$$d_c = C_c \alpha \frac{\Delta V}{V}$$

Chromatic aberration

$$d_d = 1.22 \frac{\lambda}{\alpha}, \lambda = \frac{1.2}{\sqrt{V}} nm$$

Diffraction

Helium Ion Microscope, Orion Plus, System Review



Beam spot: 3.5 Å

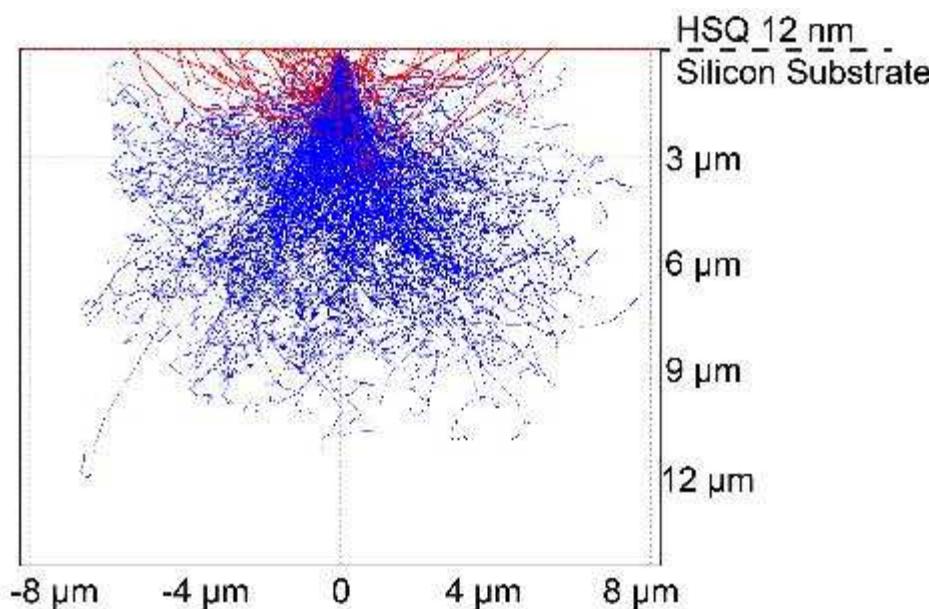
~\$2M

- HIM SE Mode Resolution
 - $\leq 0.35 \text{ nm}$
- Beam Landing Energy
 - 10 to 35 keV
- Beam Current
 - .1pA - 25pA
- Detectors
 - Everhart Thornley for Secondary Electrons (SE) imaging
 - MCP for Rutherford Backscattered Ion imaging (RBI)
 - SE & RBI images acquired simultaneously
- In-Situ Chamber and Sample Cleaning
 - Avoids carbon contamination
- Sample Neutralization
 - Maintained by low energy electron flood
 - Flood electrons are line or frame interlaced with the ions to compensate for any positive sample surface charge

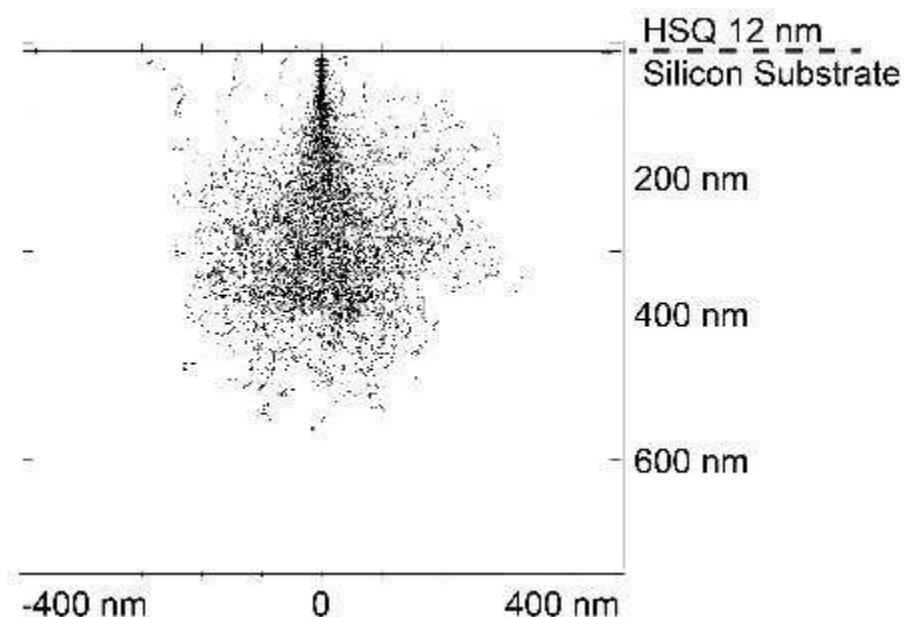
He Ion is Scattered Over Shorter Ranges

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35 KeV Electrons



35 KeV He⁺



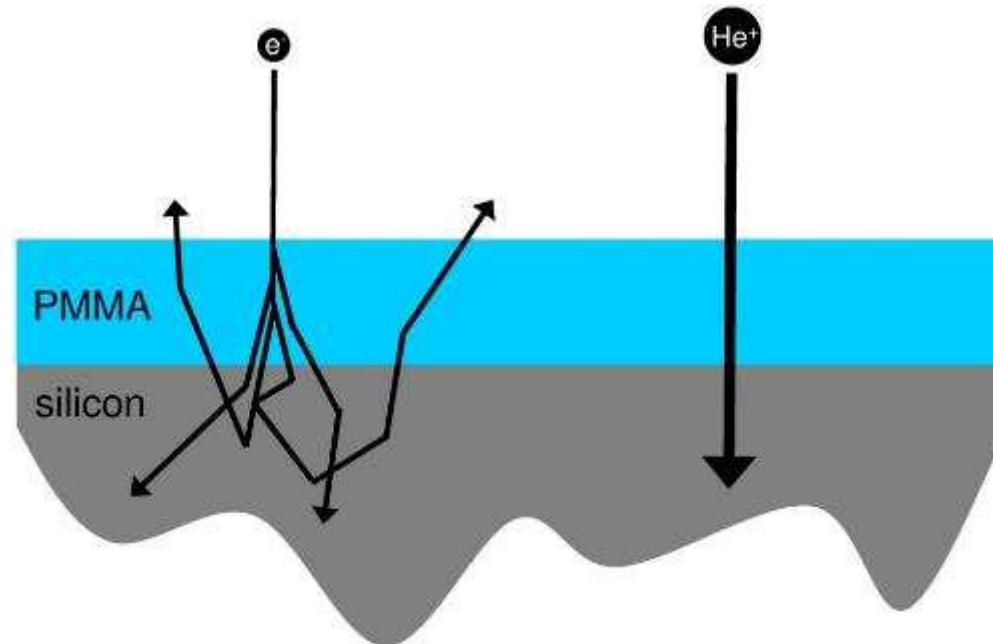
W.-D. Li, W. Wu and R. S. Williams, Journal of Vacuum Science & Technology B: Microelectronics and Nanometer Structures 30 (6), 06F304 (2012).

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He Ion: Much Less Proximity Effect

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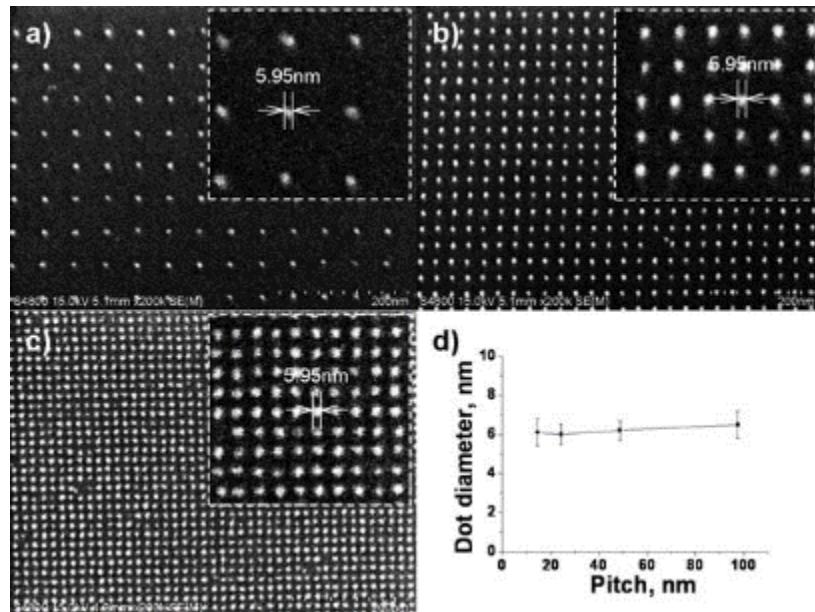
Beam scattering



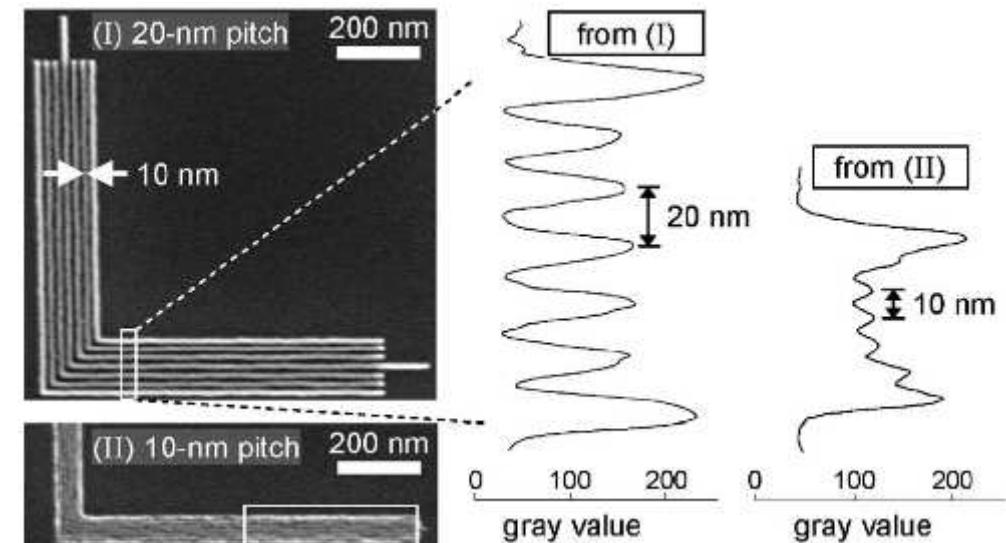
Small spot + little proximity effect --> better beam for lithography!

Helium Ion Beam Lithography

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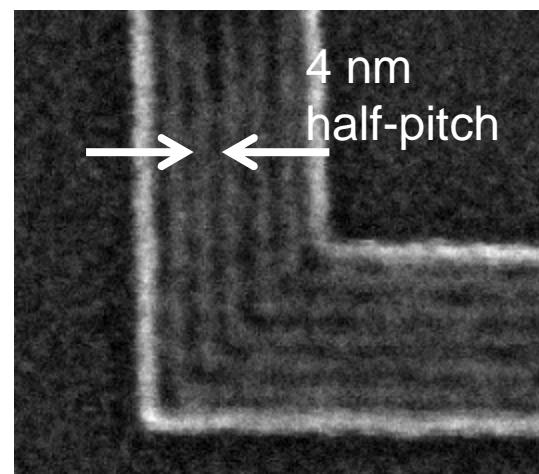
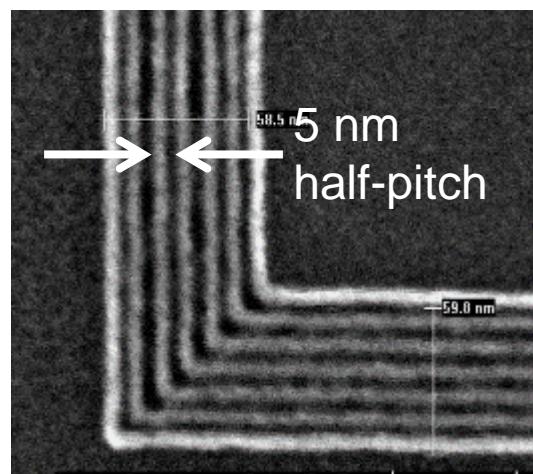
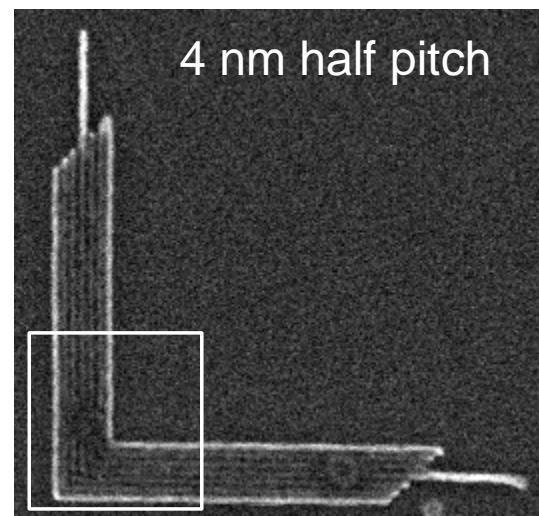
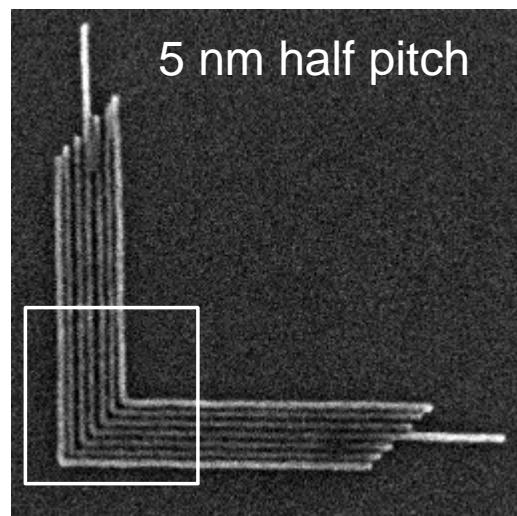
V. Sidorkin et al, J. Vac. Sci. Technol. B, 2009



D. Winston et al, J. Vac. Sci. Technol. B, 2009

HIBL for Sub-5 nm Patterning on HSQ Resist

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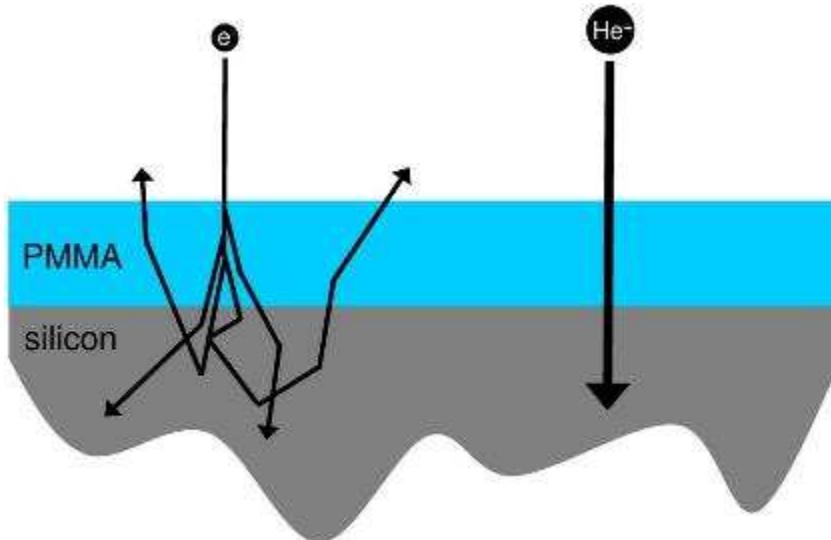
W.-D. Li, W. Wu and R. S. Williams, Journal of Vacuum Science & Technology B:
Microelectronics and Nanometer Structures 30 (6), 06F304 (2012).



He Ion: Much Less Proximity Effect

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Beam scattering



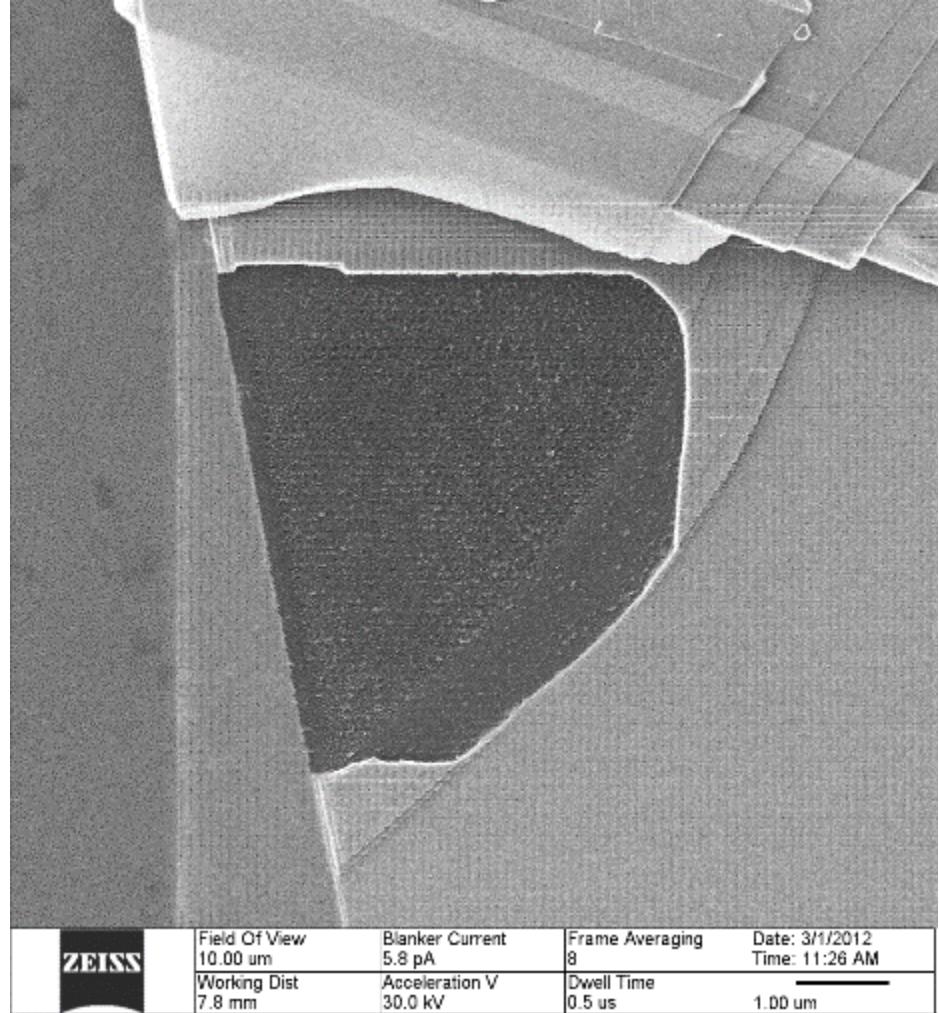
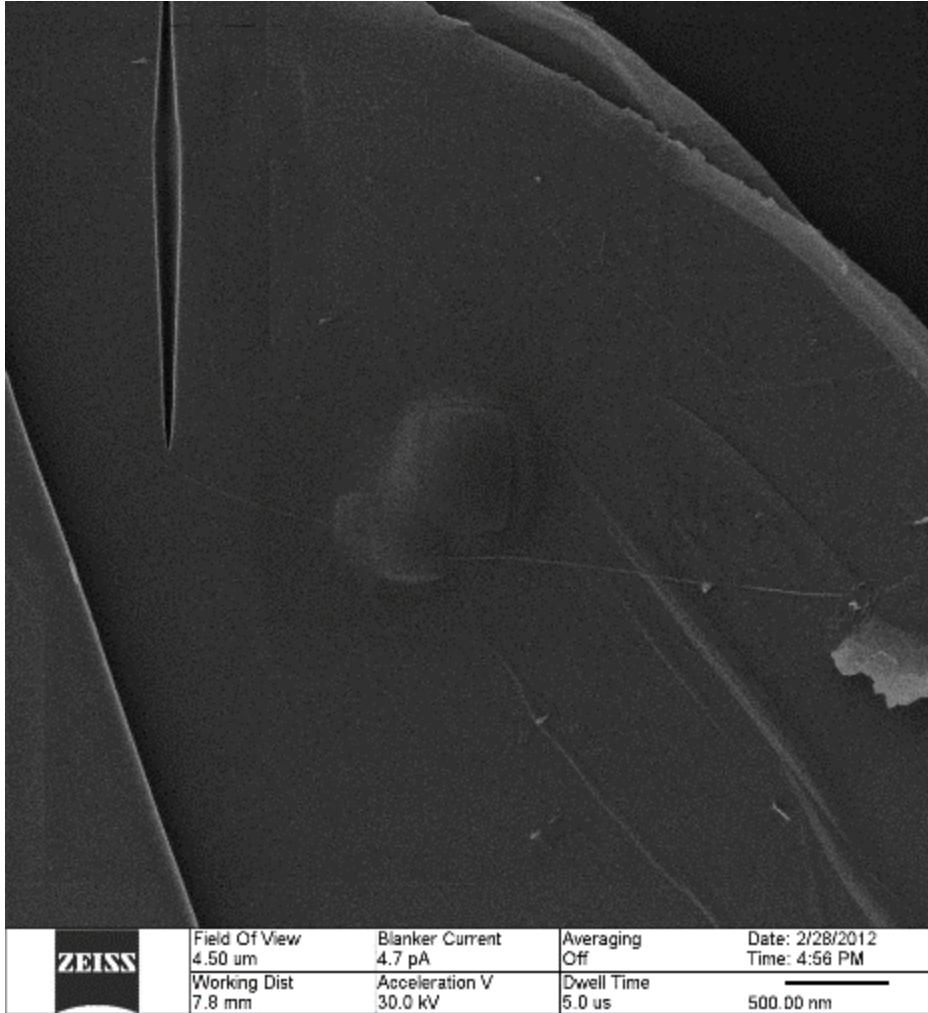
- Small spot + little proximity effect --> better beam for lithography!

Issues with He ion beam:

- Slow (low beam current)
- He ion beam is not for every substrate (He bubble formation)

Helium Bubbles

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Combination of HIBL and NIL to Reach Single-digit Design at USC Low-cost and High Throughput

1. Fabricate NIL template using a scanning helium ion beam

Expecting superior resolution compared with EBL based fabrication



2. NIL to transfer high-resolution patterns

Molecular resolution; low cost; and high throughput

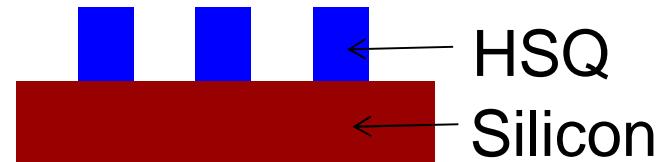


3. Device fabrication at sub-10 nm

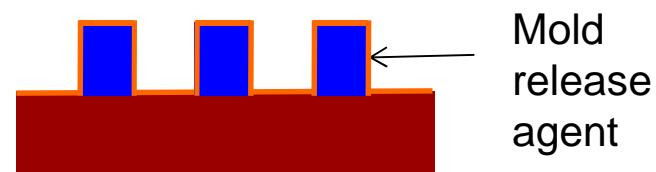
Nanoimprint Using HIBL Template

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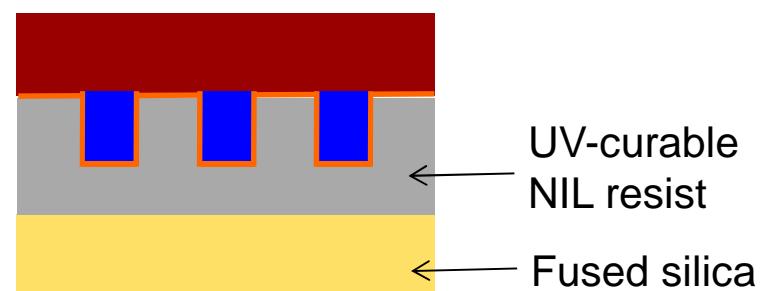
Template after HIBL
and development



Short exposure to O₂ plasma and
coating of mold release agent

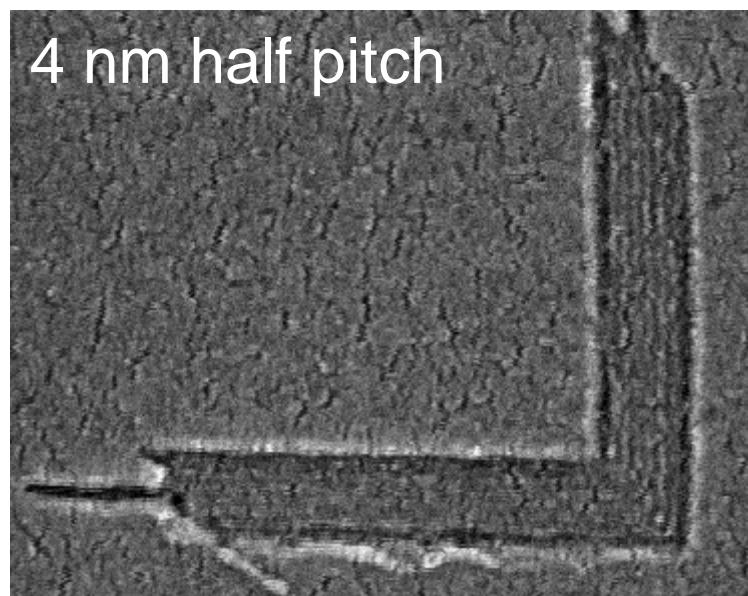
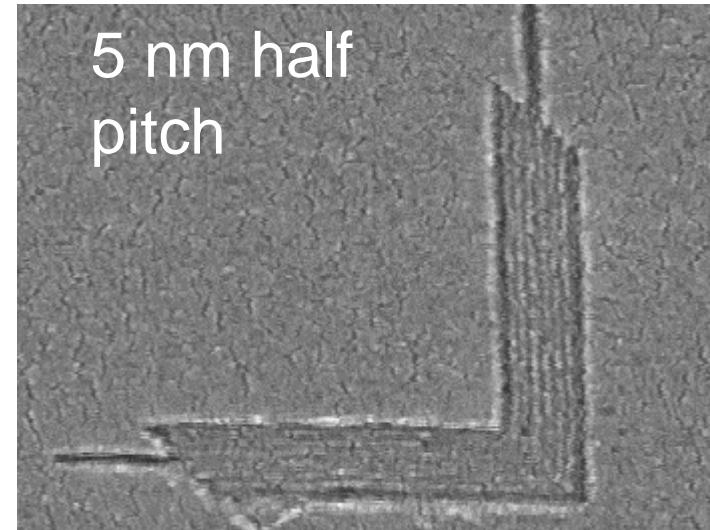
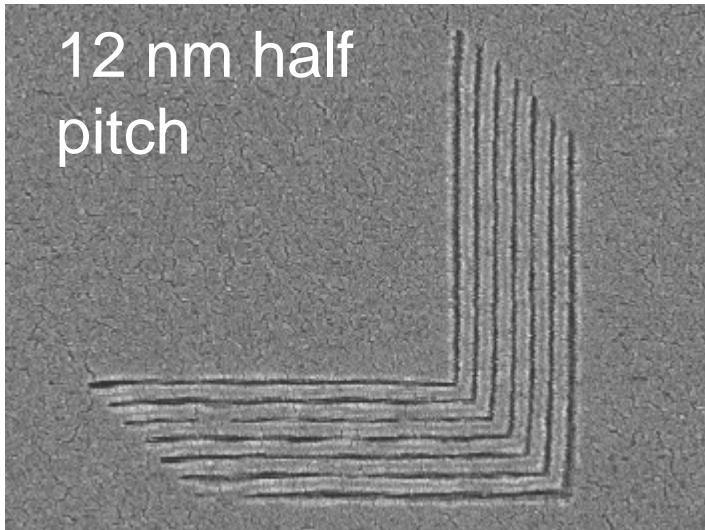


UV nanoimprint using
HIBL template



Imprinted Resist with 4-nm Half-pitch Lines

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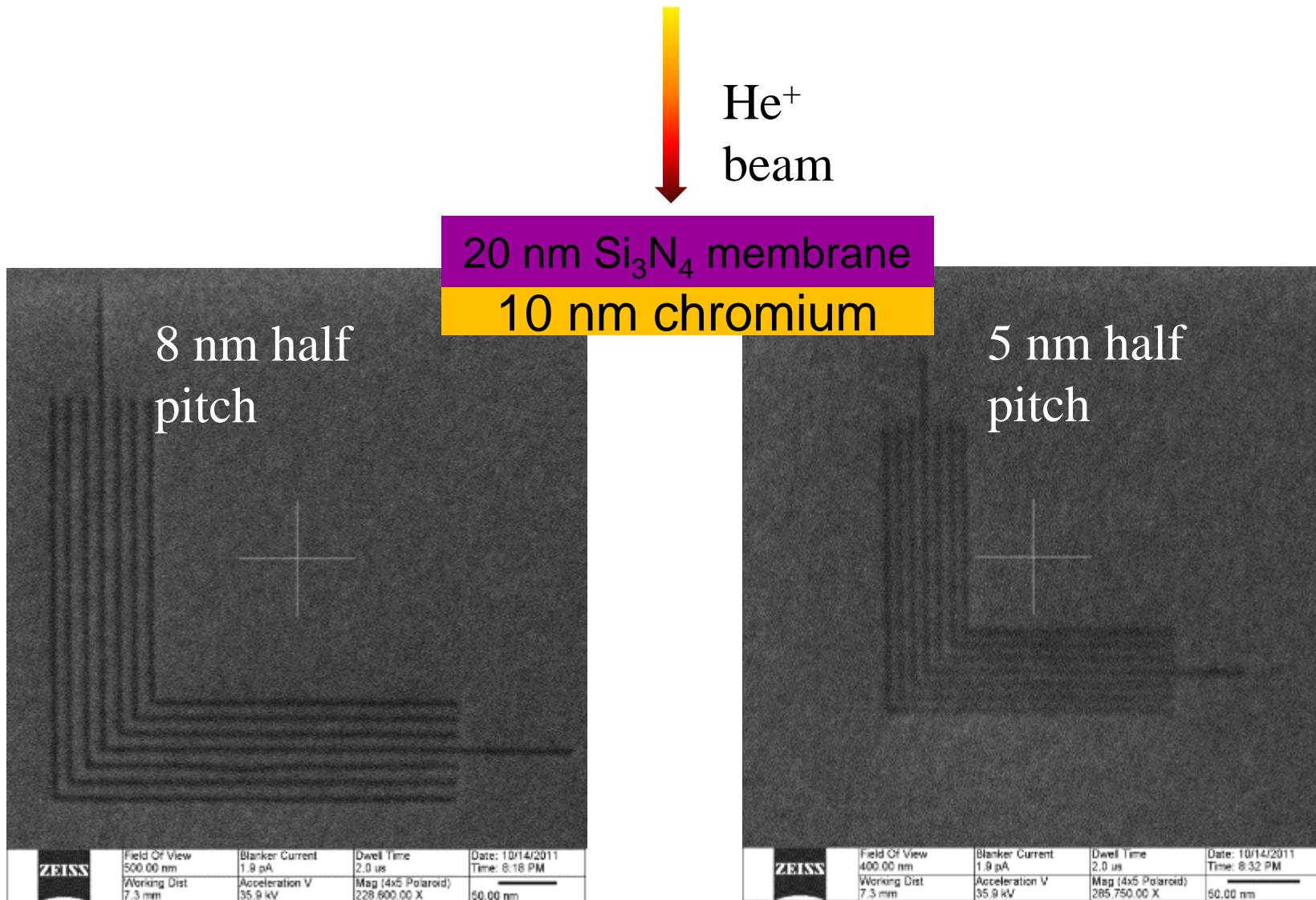
Sample coated with 2 nm platinum
and imaged under XL30 SEM at
20kV

W.-D. Li, W. Wu and R. S. Williams, Journal of Vacuum Science & Technology B: Microelectronics and Nanometer Structures 30 (6), 06F304 (2012).

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5 nm Half Pitch Lines Patterned in 10 nm Thick Chromium USC



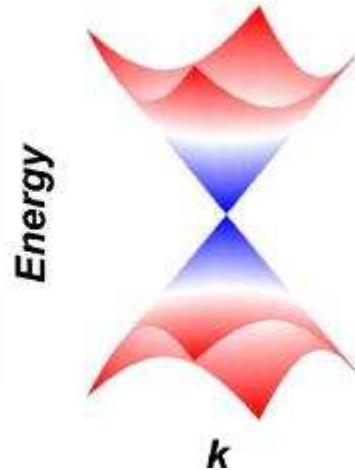
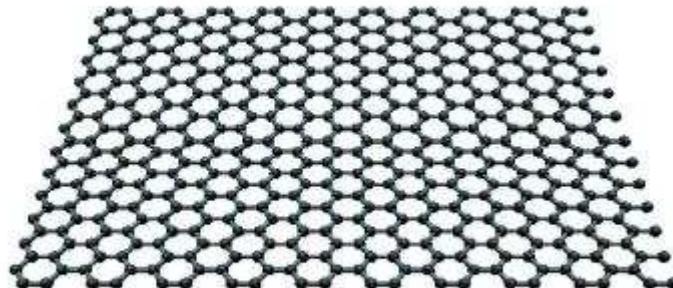
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Sub-5 nm Graphene Nanoribbons

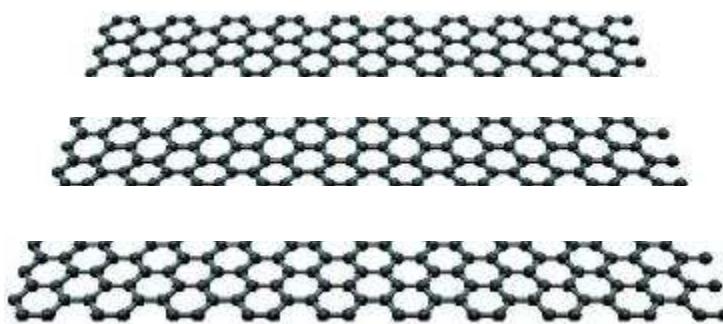
Create Bandgap with Graphene Nanoribbon

Graphene



- High mobility
- Zero bandgap

Graphene Nanoribbon



- $\Delta E \approx \frac{\alpha}{w}$
- $\alpha \approx 0.2 \sim 0.8 \text{ eV} \cdot \text{nm}$

K. S. Novoselov, A. K. Geim, S. V. Morozov, D. Jiang, Y. Zhang, S. V. Dubonos, I. V. Grigorieva and A. A. Firsov, Science 306 (5696), 666-669 (2004).

M. Y. Han, B. Özyilmaz, Y. Zhang and P. Kim, Physical Review Letters 98 (20), 206805 (2007).

X. Li, X. Wang, L. Zhang, S. Lee and H. Dai, Science 319 (5867), 1229-1232 (2008).

Patterning of Graphene Nanoribbons using He Ion Beam USC

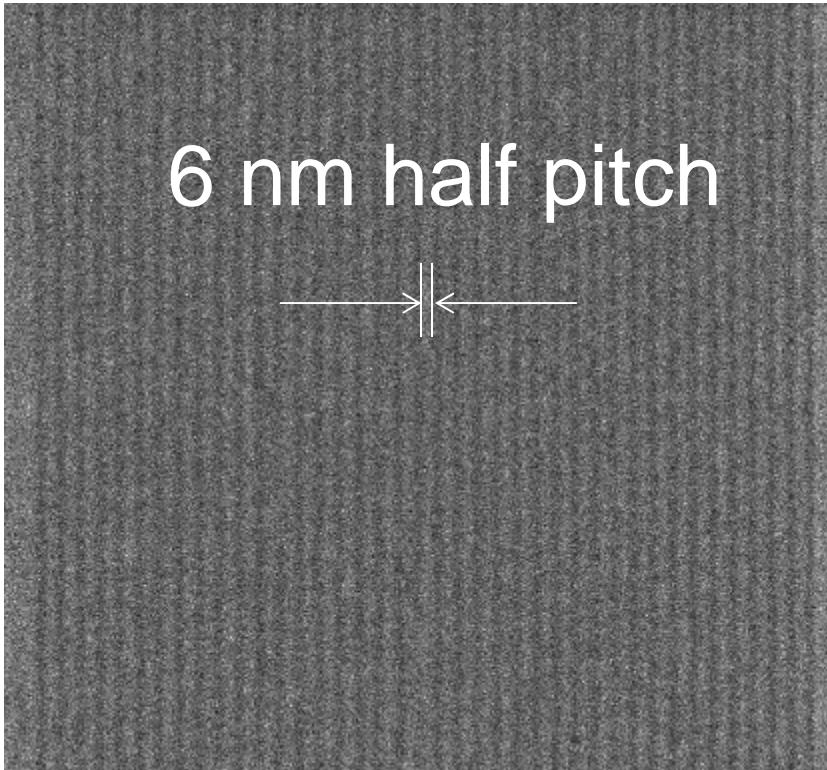


- Single layer of Graphene on 50 nm SiO₂/Si
- 30 KV
- 5μm aperture
- 0.7 pA beam current
- Dose: 5 nC/cm
- HIM images
- **5 nm half-pitch!**

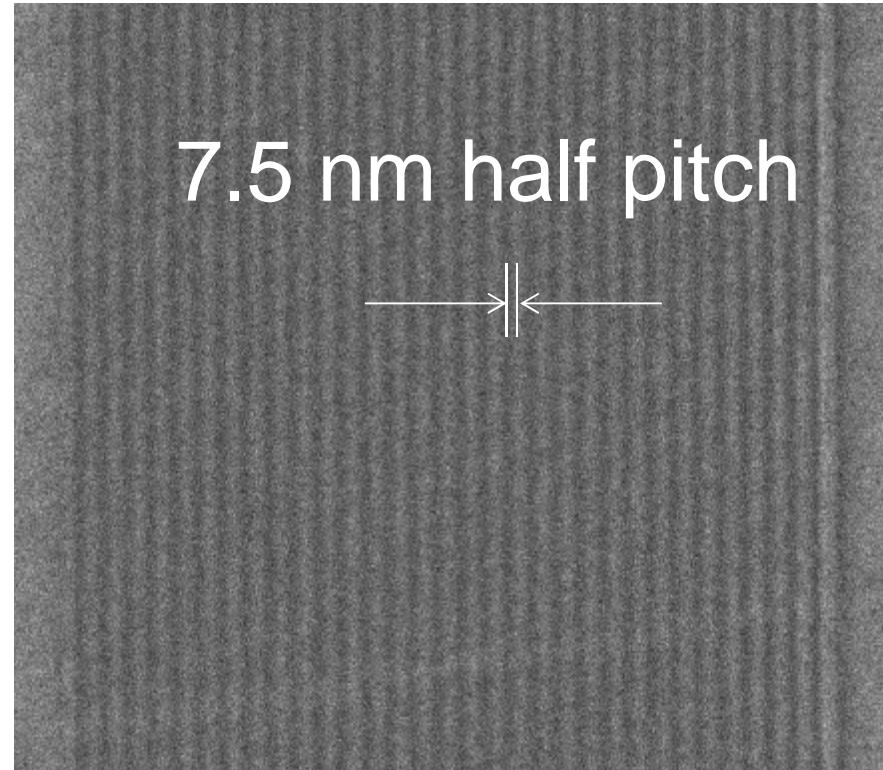
Ahmad N. Abbas, He Liu, Yuhang Yao, Gang Liu, Chongwu Zhou, Douglas A. A. Ohlberg, R. Stanley Williams and Wei Wu, EIPBN 2013
A. N. Abbas, G. Liu, B. Liu, L. Zhang, H. Liu, D. Ohlberg, W. Wu and C. Zhou, Acs Nano 8 (2), 1538-1546 (2014).

	Field Of View 1.10 um	Blanker Current 0.5 pA	Averaging Off	Date: 3/1/2012 Time: 4:42 PM
	Working Dist 7.8 mm	Acceleration V 30.0 kV	Dwell Time 10.0 us	100.00 nm

Patterning of Graphene Nanoribbons using He Ion Beam USC



6 nm half pitch



7.5 nm half pitch

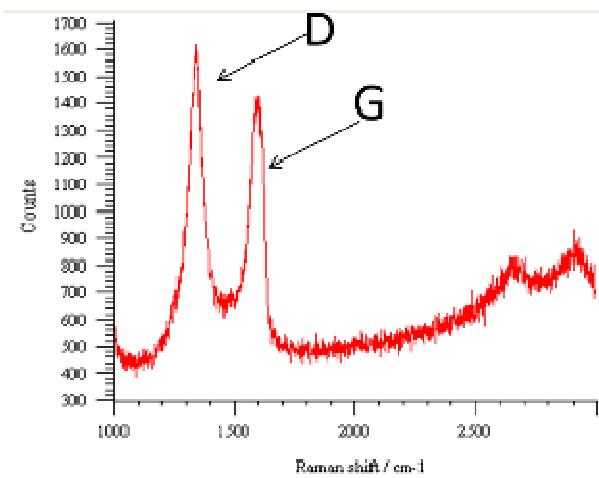
Benchmark Graphene Line-edge roughness with Raman Spectroscopy

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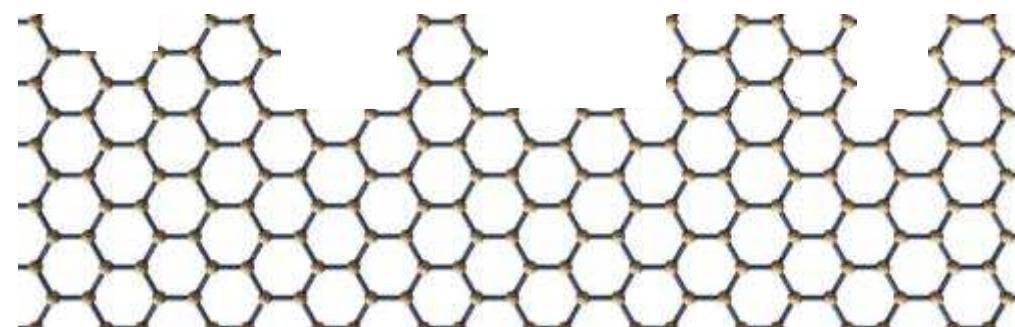
How smooth are those line edges?

- Beyond the resolution of SEM, HIM...
- TEM? Maybe...
- How about Raman spectroscopy?

10 nm half-pitch GNRs by He ion beam milling



- G: breathing mode
- D: defect mode, mainly from edges
- Rougher edges, more atoms on the edges, so higher D peak
- Using IG/ID as benchmark of the smoothness of edges



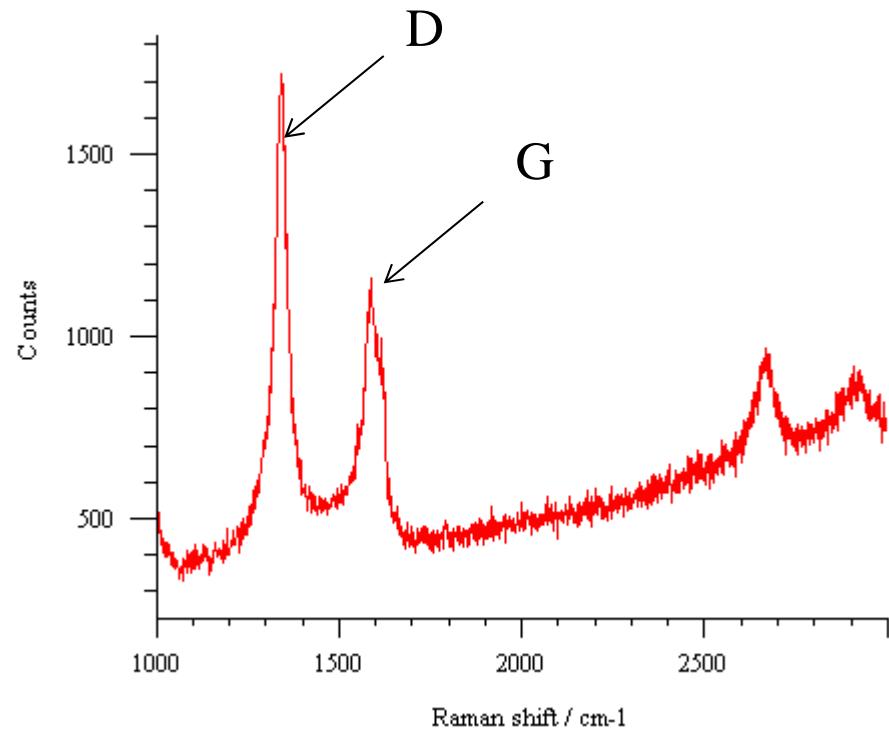
A. C. Ferrari, J. C. Meyer, V. Scardaci, C. Casiraghi, M. Lazzeri, F. Mauri, S. Piscanec, D. Jiang, K. S. Novoselov, S. Roth and A. K. Geim, Phys. Rev. Lett. **97** (18), 187401 (2006).

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Benchmark Graphene Line-edge roughness with Raman Spectroscopy

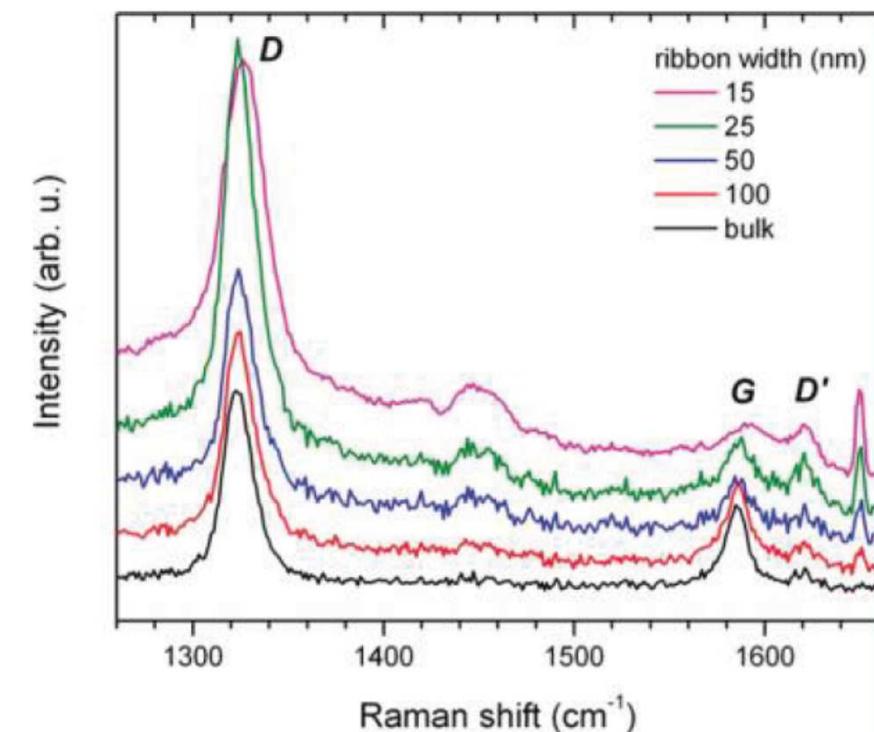
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15 nm half-pitch GNRs by He ion beam milling



Higher IG/ID means smoother edges.

Comparison:
GNRs patterned by EBL

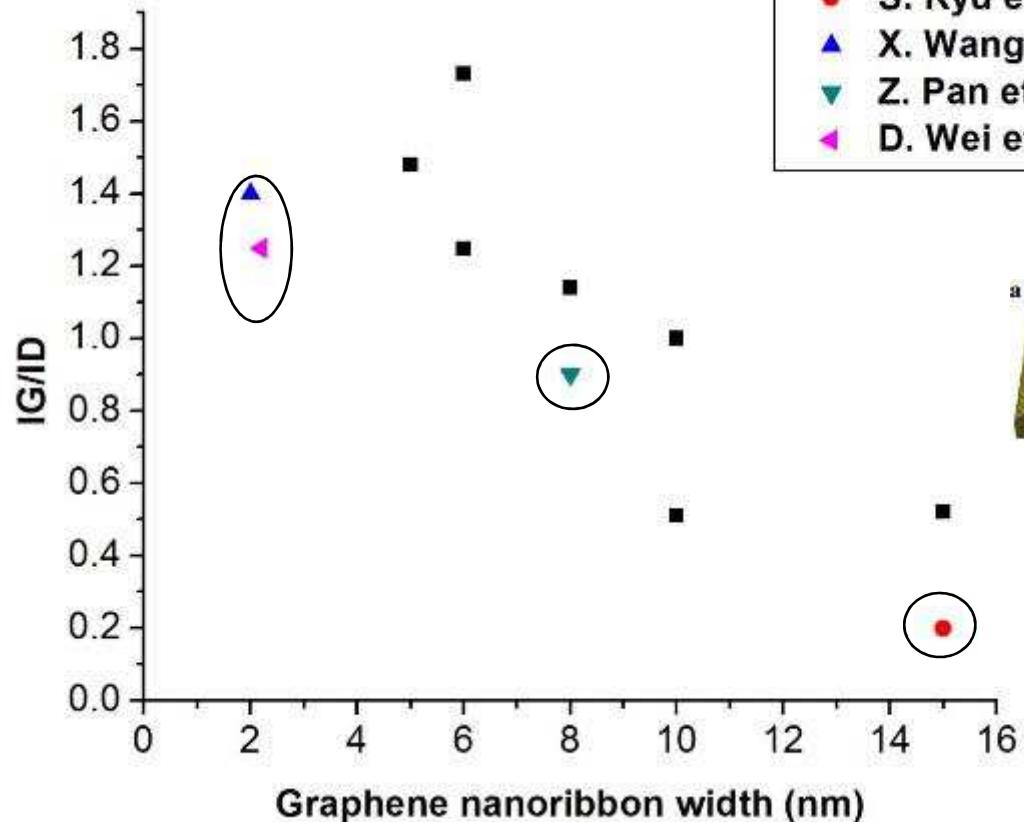


S. Ryu, J. Maultzsch, M. Y. Han, P. Kim and L. E. Brus, Acs Nano 5 (5), 4123-4130 (2011).

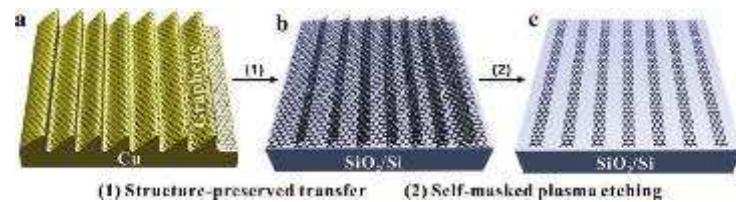
Comparison with Reported Raman Spectra Shows Smoother Line Edges

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Unzipped SWCNT



- This Work
- S. Ryu et al.
- ▲ X. Wang et al.
- ▼ Z. Pan et al.
- ◀ D. Wei et al.



Wrinkle engineering

EBL+O₂ RIE

S. Ryu, J. Maultzsch, M. Y. Han, P. Kim and L. E. Brus, *Acs Nano* **5** (5), 4123-4130 (2011).

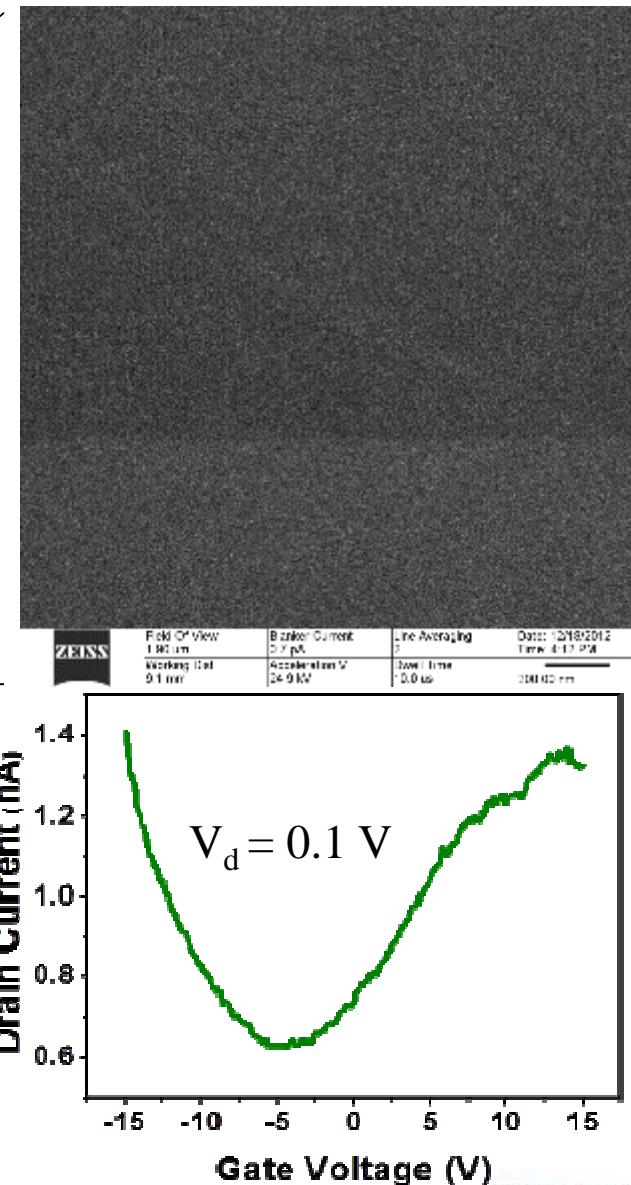
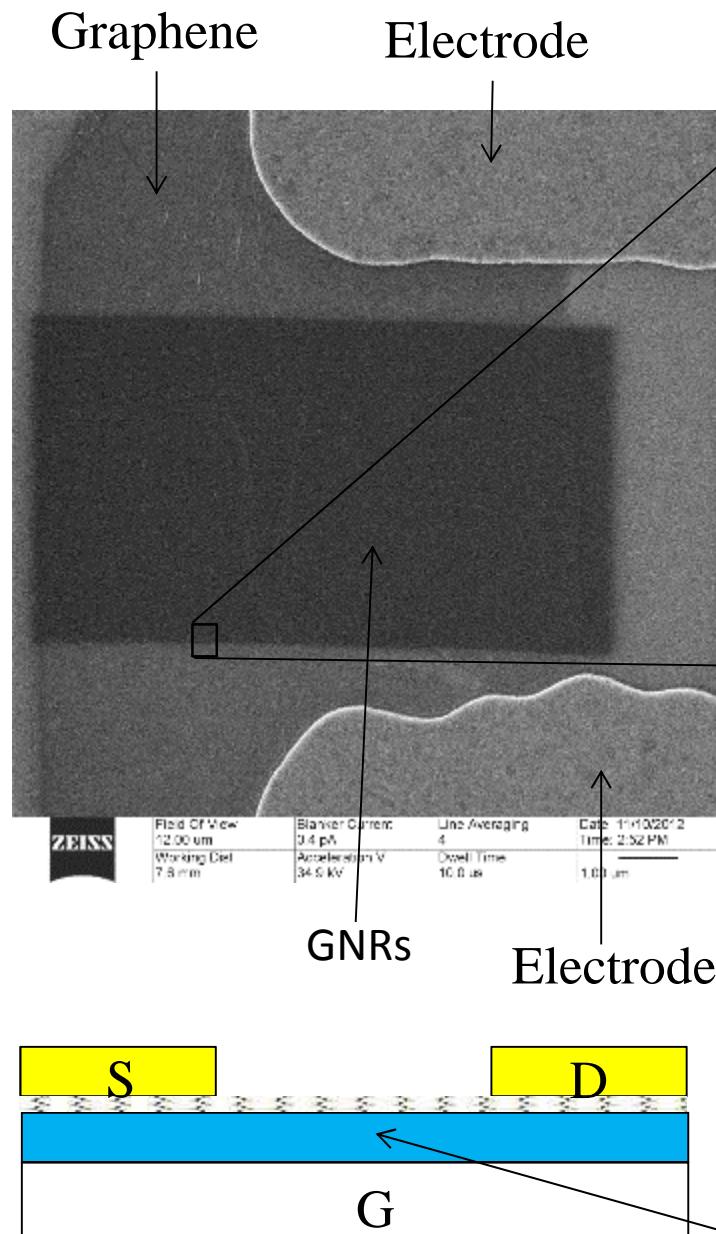
Z. Pan, N. Liu, L. Fu and Z. Liu, *Journal of the American Chemical Society* **133** (44), 17578-17581 (2011).

X. Wang, Y. Ouyang, X. Li, H. Wang, J. Guo and H. Dai, *Physical Review Letters* **100** (20), 206803 (2008).

D. Wei, L. Xie, K. K. Lee, Z. Hu, S. Tan, W. Chen, C. H. Sow, K. Chen, Y. Liu and A. T. S. Wee, *Nat Commun* **4**, 1374 (2013).

GNR MOSFET

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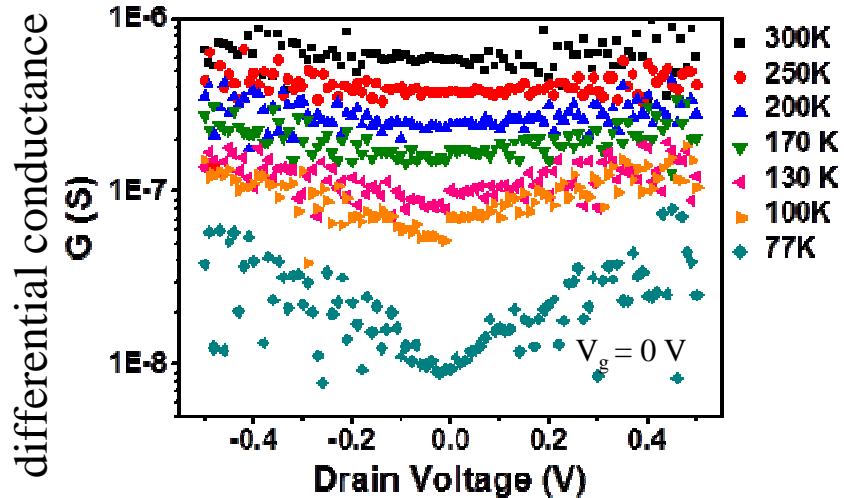
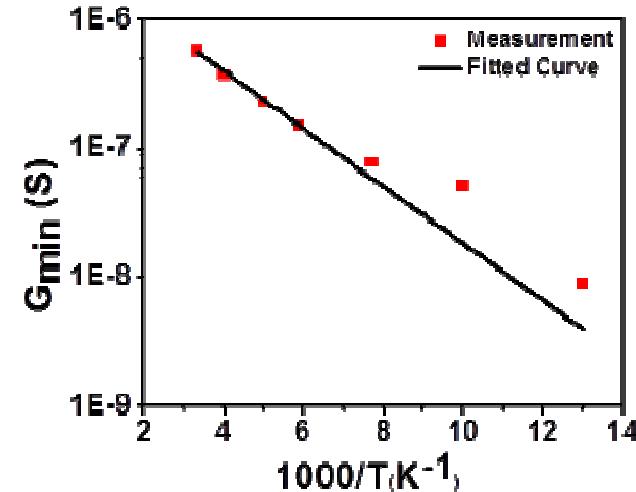
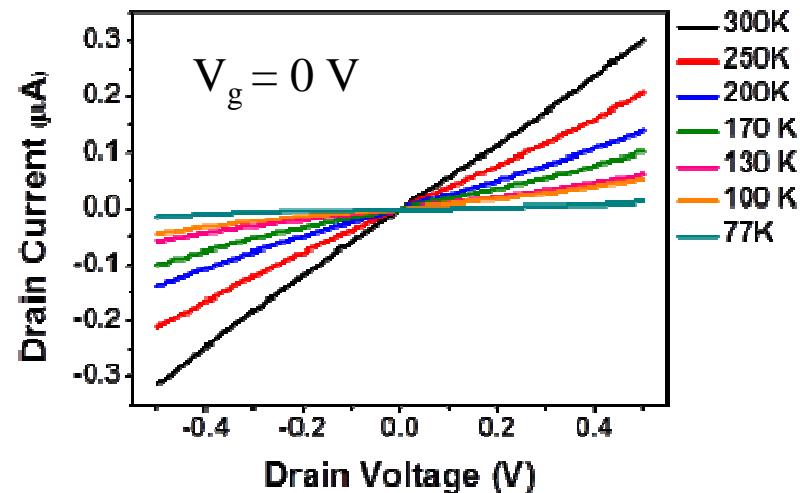


The gate dielectric got damaged by He^+ ion.

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5 nm GNR Has a Bandgap of 88 meV

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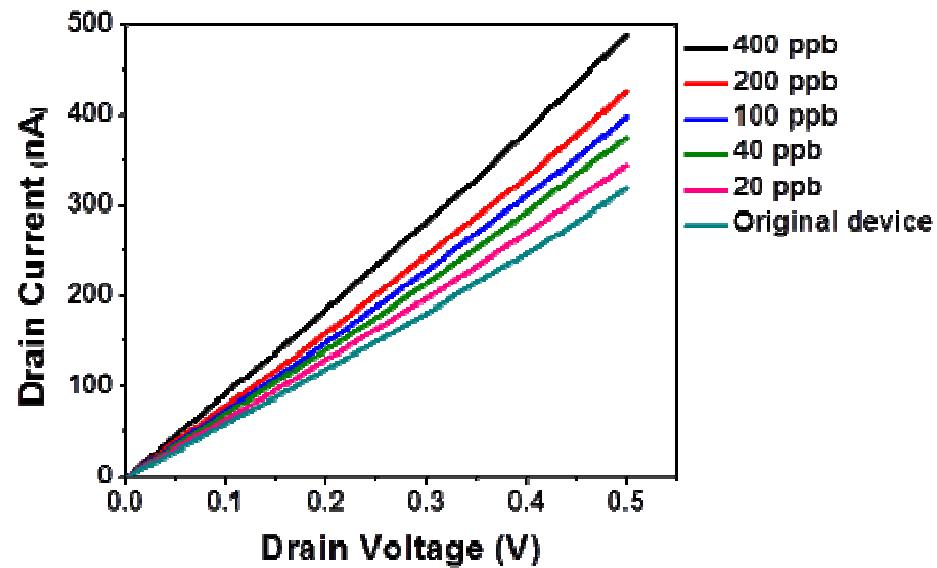
$$G_{min} = G_1 e^{\frac{-E_A}{K_B T}}$$

$$E_A = 44 \text{ meV}$$

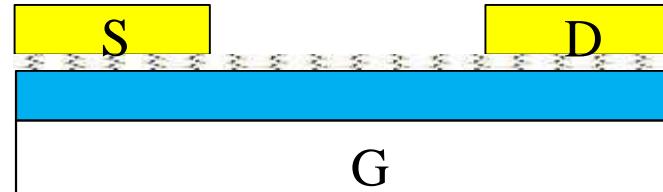
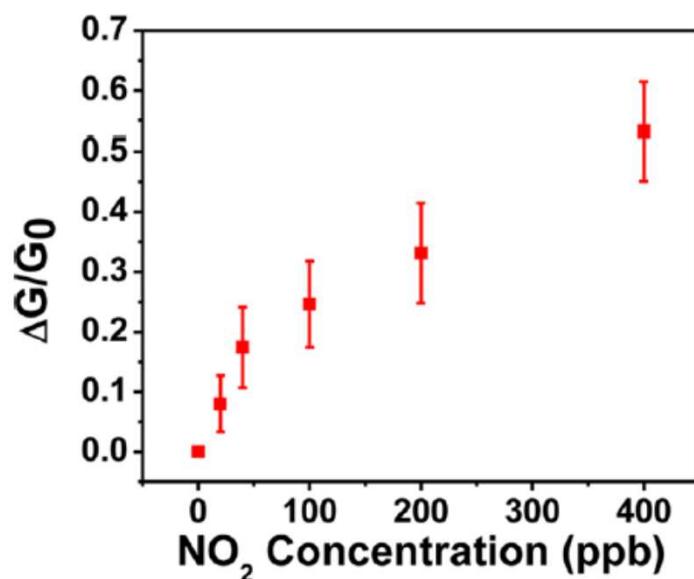
$$E_G \geq 2 E_A = 88 \text{ meV}$$

GNR FET as Gas Sensor

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- NO_2 acts as an electron attractor
- bandgap opening provides higher sensitivity
- Edge states are more active site to bond with NO_2
- Safe level of NO_2 is 0.2 ppm
- Detection of 20 ppb NO_2 has been demonstrated



Summary



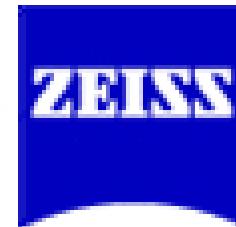
- Sub-5 nm patterning using
 - HIBL and
 - NIL
 - Direct He ion milling
- Patterning of GNRs
 - Better line-edge roughness than reported results with Raman data.
 - GNR FET
 - 88 meV bandgap
 - NO₂ gas sensor

Acknowledgement

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i n v e n t



We make it visible.



香港大學
THE UNIVERSITY OF HONG KONG



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Thank you...

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